

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7079824

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
QIU YI ZHANG	10/20/2021
ZHI BIN LI	10/20/2021
RUI LING WU	10/20/2021
WEI MING DONG	10/19/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SIEMENS SHENZHEN MAGNETIC RESONANCE LTD.
<b>Street Address:</b>	GAO XIN ZHONG ER DAO, GAO XIN QU, ZHONG QU
<b>City:</b>	SHENZHEN
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	518057
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17412510
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(312)258-5600
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	(312) 258-5615
<b>Email:</b>	patents-ch@schiffhardin.com
<b>Correspondent Name:</b>	SCHIFF HARDIN LLP
<b>Address Line 1:</b>	233 S. WACKER DR.
<b>Address Line 2:</b>	SUITE 7100
<b>Address Line 4:</b>	CHICAGO, ILLINOIS 60606
<b>ATTORNEY DOCKET NUMBER:</b>	26965-6204 P21,0078
<b>NAME OF SUBMITTER:</b>	JAY R. BOMBIEN
<b>SIGNATURE:</b>	/Jay R. Bombien/
<b>DATE SIGNED:</b>	12/17/2021
<b>Total Attachments: 3</b>	
source=P210078 Assignment inventors to SSMR Ltd#page1.tif	
source=P210078 Assignment inventors to SSMR Ltd#page2.tif	



**ASSIGNMENT**

For good and valuable consideration, I (We),

**Wei Ming Dong**, residing at Lvhai Mingdu 2-501, Xuefu Road, Nanshan District, Shenzhen, 518000, CN, citizen of CN

**Qiu Yi Zhang**, residing at Yang Guang Hai 2C-1915 Yue He Road, Xi' Xiang Street, Bao An district, Shenzhen, 518115, CN, citizen of CN

**Zhi Bin Li**, residing at 27-204 Yu Kang Hua Yuan, Shenzhen, China 518057, CN, citizen of CN

**Rui Ling Wu**, residing at KangQiao Garden, Longgang District, Shenzhen, 518114, CN, citizen of CN

hereafter individually or collectively referred to as "Assignor(s)"; hereby

- (1) (A) acknowledge having previously assigned, sold and transferred to **Siemens Shenzhen Magnetic Resonance Ltd.**, a corporation organized and existing under the laws of CHINA, having its principal place of business at Gao Xin Zhong Er Dao, Gao Xin Qu, Zhong Qu, Shenzhen, 518057, hereinafter "Assignee", its successors, assigns and legal representatives, or to a predecessor of Assignee, pursuant to

(i) the laws of CHINA or

(ii) a Patent & Secrecy Agreement or similar legal document such as, without limitation, an employee agreement executed at the time of entering into the employment of, or executed as a condition of continuing employment with, the Assignee or a predecessor of the Assignee, the entire right, including any and all priority rights, title and interest, in and for the United States and all foreign countries, in and to any and all inventions or improvements which are disclosed in an invention disclosure and/or in the below-identified documents currently filed with this Assignment, already filed or granted for Letters Patent (in which case, if any provision of the subject Assignment that is in conflict with or is in addition to any provision in the prior agreement(s) or assignment(s) then this Assignment shall govern, take precedence, and be of legal effect), or

- (B) (i) to the extent such laws of CHINA or such Patent & Secrecy Agreement or similar legal document failed or fails, in whole or part, to have assigned, sold or transferred the entire right (including priority rights), title and interest, in and for the United States and all foreign countries, in and to all inventions or improvements which are disclosed in the below-identified application(s) or pending application(s) or granted Letters Patent, or

(ii) if no such agreement(s) exist assigning, selling or transferring any such right (including priority rights), title or interest;

then for good and valuable consideration, Assignor(s) now and hereby, effective Nunc Pro Tunc on the filing date of the below identified patent application(s), pending patent application(s) or granted Letter Patent(s), assign, sell and transfer(s) to Assignee, its successors, assigns and legal representatives,

(i) the entire right, (including all priority rights), title and interest in and for the United States and all foreign countries, in and to any and all inventions and/or improvements which are disclosed in the following identified; patent application(s),

pending patent application(s) or granted Letter Patent(s). I/we hereby authorize the Assignee or its designee to insert below the information when known


Patent Application Title: Wireless Power feedback loop and control system for wireless coil in MRI system  
Filing Date: 26 Aug 2021  
Filing Number: 17/412,510  
Internal Case Number(s): 2020P12042 US

and

(ii) in and to said application(s) or granted patents and all applications claiming priority to said application or granted patent, including, without limitation, all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of the inventions and/or improvements; and

(iii) in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on the inventions and/or improvements;

- (2) agree that said Assignee may apply for and receive Letters Patent for said inventions and/or improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said inventions and/or improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said inventions and/or improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said inventions and/or improvements and for vesting title to said inventions and/or improvements, in said Assignee, its successors, assigns and legal representatives; and
- (3) covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

  
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Wei Ming Dong

2021. 10. 19  
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Date

  
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Qiu Yi Zhang

2021. 10. 20  
\_\_\_\_\_  
Date

Zhibin Li  
Zhi Bin Li

2021. 10. 20  
Date

Rui Ling Wu  
Rui Ling Wu

2021. 10. 20  
Date

Companies Representative(s)  
Siemens Shenzhen Magnetic Resonance Ltd.

Signature(s)	<u>[Signature]</u>	<u>[Signature]</u>	<u>[Signature]</u>
Name(s)	<u>Schneck, Andreas</u>	<u>Qiu Yan Hua</u>	<u>Bai Ya Jun</u>
Title	<u>SSMR General Manager</u>	<u>SSMR Vice President of Finance</u>	<u>Head of IP China</u>
Date	<u>Andreas Schneck</u>	<u>18 NOV 2021</u>	<u>18 SEP 2021</u>

18 NOV 2021